	Material Comp © Copyright 2005. I international and Par	PC, Bannockb	ourn, Illinois. A	All rights reserved u ntions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the sub ncompasses a	stances wi all lower le	ithin the manufactur evel materials for w	er listed i hich the n	tem. Note: if nanufacturer	the item is an as has engineering	ssembly with low responsibility.	
752-21.1	.1 IPC Web Site for Information on IPC-1752 Standard Form Type Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier	r Information														
Company name* Company unique ID				1	Unique ID Authority				Response Date*						
nsemi												2023-06-08			
Contact N	ame		Title - Contact]	Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	d Representative*		Title - Repre	Title - Representative			Phone - Representative*			Email - Representative*					
roduct-E	Env-Stewards		Product Env	iro Compliance			NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number	Imber Mfr Item Name Effective Date Version		Ma	Manufacturing Site		Weight*	UOM	Unit Type				
		STK534U342C-E 3phase inverter HIG		IC		2023-06-08		VN	VN2		13900.0	mg	Each		
Ianufa	cturing Proccess Informa	tion													
Terminal Plating / Grid Array Material			Cerminal Base	e Alloy J-STD-020 MSL Rating			Peak Process Body Temperature Max Time at Peak			Temperature Number of Reflow Cycles					
	Matte Tin (Sn) - annealed	C	CU Alloy	1	NA		0		С	30	secon	ids 3			
omments															
or more i	information regarding material	composition	please refer to	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-ethers)	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexcess encompass all such components.Supplier cert as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided certification in this paragraph.If the Company	ted biphenyls and/or polybrominated dip of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ve relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr source of the Supplier's liability and the	henyl ethers (each a "RoHS restricted subs ndicate below which, if any, RoHS exempt ovides in this form using appropriate meth will rely on this certification in determinin ers in completing this form, and that Suppl num, itssuppliers have provided certificatio eement with respect to the identified part,t Company's remedies for issues that arise r	stance") in exce ion you believe ods to ensure i g the compliar ier may not ha ons regarding t he terms and co	ropean Union member states) of the part identifiess of the applicable quantity limit identified able may apply. If the part is an assembly with low is accuracy and that such information is true and ce of its products with European Union member independently verified such information. How heir contributions to the part, and those certifica onditions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for se	elected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7c-I Electrical and electronic c	omponents containing lead in a glass o	r ceramic other than dielectric ceramic	in capacitors,	e.g. piezoelectronic devices, or in a glass or c	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to ha			ice drop-dowi	n. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature R	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measur
Ceramic Substrate	3844.87	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		48.0609	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		189.5521	mg
			В	Nickel (Ni)	7440-02-0		6.5363	mg
			Supplier	Acrylic resins	Proprietary Data		2.6914	mg
			Supplier	Copper (Cu)	7440-50-8		258.3753	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		1.9224	mg
			Supplier	Aluminum (Al)	7429-90-5		3337.7317	mg
Chip Parts	30.73	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0092	mg
			Supplier	Silver (Ag)	7440-22-4		1.0694	mg
			Supplier	Epoxy resins	129915-35-1		0.3165	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068- 38-6		0.0246	mg
			Supplier	Tin (Sn)	7440-31-5		1.0479	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0277	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.8328	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		7.1755	mg
			Supplier	Phenolic resins	Proprietary Data		0.0553	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0092	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		17.556	mg
			В	Nickel (Ni)	7440-02-0		1.2753	mg
			А	Lead Oxide (PbO)	1317-36-8	7c	0.1506	mg
			Supplier	Chromium Trioxide (Cr2O3)	1308-38-9		0.0092	mg
			Supplier	Copper (Cu)	7440-50-8		1.1708	mg
Die	25.26	mg	Supplier	Silicon (Si)	7440-21-3		25.26	mg
Die Attach	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.0549	mg
			В	Antimony (Sb)	7440-36-0		0.0051	mg
leat Sink	850.56	mg	Supplier	Silver (Ag)	7440-22-4		136.0896	mg
			Supplier	Copper (Cu)	7440-50-8		714.4704	mg
ead Frame	515.59	mg	Supplier	Tin (Sn)	7440-31-5		0.3094	mg
			Supplier	Copper (Cu)	7440-50-8		515.2807	mg
Vold Compound-Black	8504.69	mg		Brominated epoxy resin	proprietary data		20.4113	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Phenolic Resin	Proprietary Data	440.5429	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	15.3084	mg
			Supplier	Carbon Black (C)	1333-86-4	34.8692	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	596.1788	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	5587.5811	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	935.5159	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	874.2822	mg
Plating	1.03	mg	Supplier	Tin (Sn)	7440-31-5	0.6377	mg
			В	Nickel (Ni)	7440-02-0	0.3923	mg
Solder Ball	61.85	mg	Supplier	Silver (Ag)	7440-22-4	1.8741	mg
			Supplier	Tin (Sn)	7440-31-5	59.5368	mg
			В	Antimony (Sb)	7440-36-0	0.0186	mg
			Supplier	Copper (Cu)	7440-50-8	0.4206	mg
Wire Bond - Al	65.36	mg	Supplier	Aluminum (Al)	7429-90-5	65.36	mg